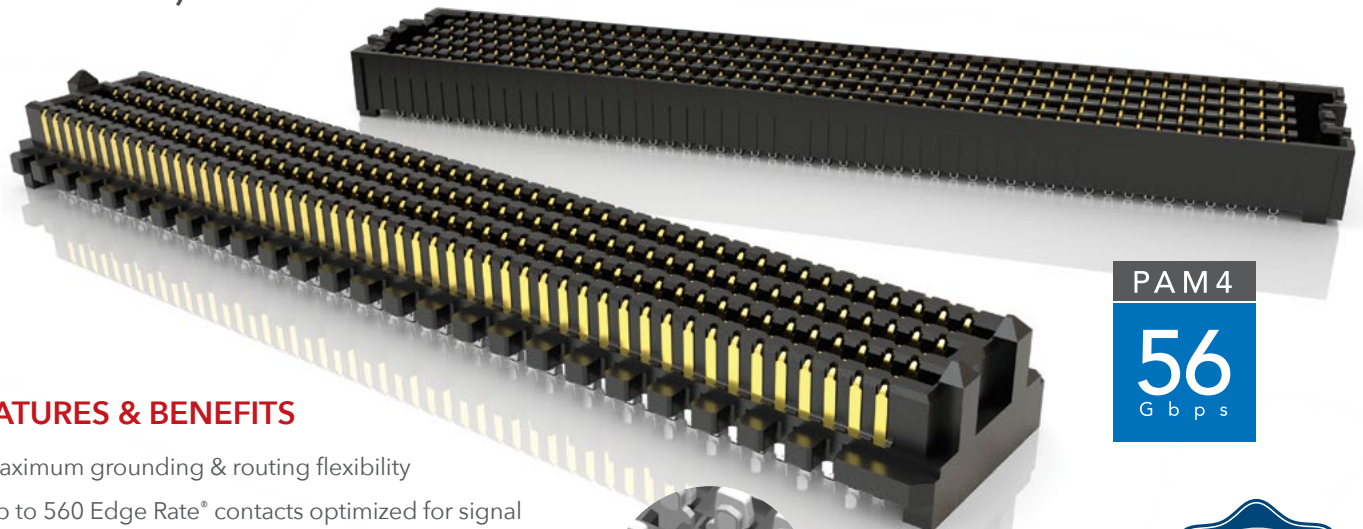




HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH

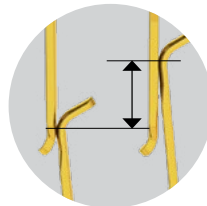


FEATURES & BENEFITS

- Maximum grounding & routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance.
- 7 mm to 40 mm stack heights
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Standards: VITA 47, VITA 57.1 FMC, VITA 57.4 FMC+, VITA 74 VNX, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand™
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit samtec.com/set



Solder Charges



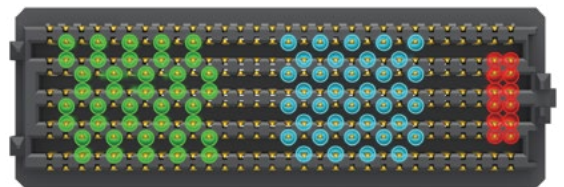
(1.12 mm) .044" Nominal Wipe

EDGE RATE
CONTACT

PAM 4
56
G b p s



MAXIMUM GROUNDING & ROUTING FLEXIBILITY



Differential Pair Single-Ended Power

| SERIES | INSULATOR MATERIAL | CONTACT MATERIAL | PLATING | OPERATING TEMP RANGE | CURRENT RATING | VOLTAGE RATING | LEAD-FREE SOLDERABLE |
|-----------------|-------------------------|--------------------------------------------|----------------------------------|----------------------|-------------------------|----------------|----------------------|
| SEAM/SEAF | Black LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | -55 °C to +125 °C | 2.7 A (10 pins powered) | 240 VAC | Yes |
| SEAM-RA/SEAF-RA | Black LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | -55 °C to +125 °C | 1.9 A (10 pins powered) | 260 VAC | Yes |
| SEAM-GP | Black LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | -55 °C to +125 °C | 2.7 A (10 pins powered) | 240 VAC | Yes |
| SEAMP/SEAFP | Natural High Temp Nylon | Copper Alloy (SEAMP) BeCu Alloy (SEAFP) | Au or Sn over 50 μ" (1.27 μm) Ni | -55 °C to +125 °C | 1.9 A (6 pins powered) | 225 VAC | Not Available |
| SEAR | Black LCP | Hard Gold Plated | Au over 50 μ" (1.27 μm) Ni | -55 °C to +125 °C | Contact Samtec | 240 VAC | Not Available |
| SEAMI | Black LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | -55 °C to +125 °C | Not Available | Not Available | Yes |

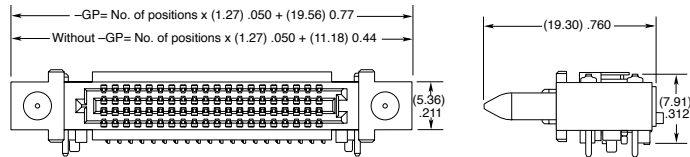
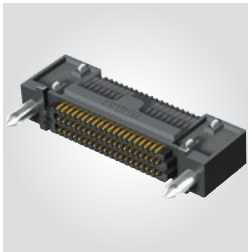
Note: Some lengths, styles and options are non-standard, non-returnable

(1.27 mm) .050" PITCH • RIGHT-ANGLE & GUIDE POST

| SERIES | POSITIONS PER ROW | 01 | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | RA | OPTIONS | "X"R |
|------------------------------|-------------------|----|---------------------------------------------------------------------------|-------------|--------------------------------------|----|--------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------|
| SEAM Right-Angle Terminal | -20 | | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail | -04 | -1 = Tin/Lead Alloy Solder Charge | | -GP = Guide Post/Hole | -TR = Tape & Reel |
| | -30 | | | -06 | | | -K = Polyimide Film Pick & Place Pad | -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) |
| SEAF Right-Angle Socket | -40 | | -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail | -08 | -2 = Lead-Free Solder Charge | | -LP Latch Post (Available with SEAF in -06 Row with 30 positions only; Required for mating to SEAC) | |
| | -50 | | | -10 | | | | |
| | | | -08 & -10 Row options require fixturing to process | | | | | |

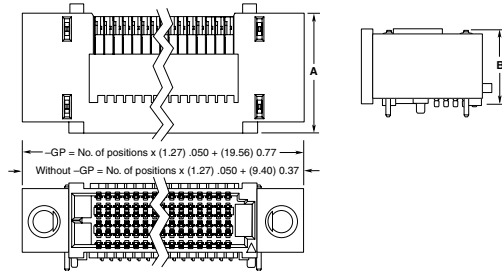
SEAM-RA

Board Mates:
SEAF, SEAF-RA,
SEAFP



SEAF-RA

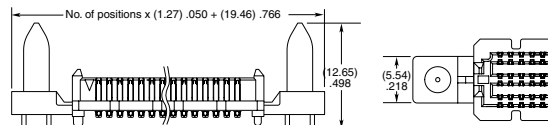
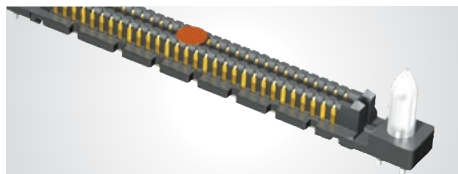
Board Mates:
SEAM, SEAMP



| NO. PINS PER ROW | A | B |
|------------------|--------------|--------------|
| -04 | (13.77) .542 | (7.91) .311 |
| -06 | (16.31) .642 | (10.45) .411 |
| -08 | (18.85) .742 | (12.99) .511 |
| -10 | (21.39) .842 | (15.53) .611 |

View complete specifications at: samtec.com?SEAM-RA & samtec.com?SEAF-RA

| SERIES | POSITIONS PER ROW | 02.0 | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | A | GP | K | "X"R |
|----------------------------------|-----------------------|------|---------------------------------------------------------------------------|-------------|--------------------------------------|---|----|---|-----------------------------------------|
| SEAM Terminal with Guide post | -20, -30, -40, -50 | | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail | -04 | -1 = Tin/Lead Alloy Solder Charge | | | | -TR = Tape & Reel |
| | | | | -06 | | | | | -K = Polyimide Film Pick & Place Pad |
| SEAM-GP | -40 | | -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail | -08 | -2 = Lead-Free Solder Charge | | | | |
| | | | | -10 | | | | | |
| | | | -08 & -10 Row options require fixturing to process | | | | | | |



View complete specifications at: samtec.com?SEAM

Note: Some lengths, styles and options are non-standard, non-returnable